



Material Content Data Sheet



Sales Product Name		BSZ088N03MS G		Issued		29. August 2013		
MA#		MA000896764						
Package		PG-TSDSON-8-21		Weight*		36.27 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.804	2.22	2.22	22165	22165
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		65	
	non noble metal	zinc	7440-66-6	0.009	0.03		261	
	non noble metal	iron	7439-89-6	0.189	0.52		5221	
	non noble metal	copper	7440-50-8	7.689	21.20	21.76	211994	217541
wire	noble metal	gold	7440-57-5	0.222	0.61	0.61	6119	6119
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1027	
	plastics	epoxy resin	-	1.919	5.29		52917	
	inorganic material	silicondioxide	60676-86-0	16.677	45.99	51.38	459807	513751
leadfinish	non noble metal	tin	7440-31-5	0.370	1.02	1.02	10203	10203
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2228	2228
solder	non noble metal	tin	7440-31-5	0.054	0.15		1500	
	non noble metal	lead	7439-92-1	1.034	2.85	3.00	28508	30008
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		130	
	non noble metal	iron	7439-89-6	0.094	0.26		2591	
	non noble metal	copper	7440-50-8	3.816	10.52	10.79	105210	107963
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		108	
	non noble metal	iron	7439-89-6	0.078	0.22		2161	
	non noble metal	copper	7440-50-8	3.182	8.77	9.00	87726	90022
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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